

FAN7371

High-Current High-Side Gate Drive IC

Features

- Floating Channel for Bootstrap Operation to +600V
- 4A/4A Sourcing/Sinking Current Driving Capability
- Common-Mode dv/dt Noise Canceling Circuit
- 3.3V and 5V Input Logic Compatible
- Output In-phase with Input Signal
- Under- Voltage Lockout for V_{BS}
- 25V Shunt Regulator on V_{DD} and V_{BS}
- 8-Lead Small Outline Package (SOP)

Applications

- High-Speed Gate Driver
- Sustained Switch Driver in PDP Application
- Energy-Recovery Circuit Switch Driver in PDP Application
- High-Power Buck Converter
- Motor Drive Inverter

Description

The FAN7371 is a monolithic high-side gate drive IC, which can drive high-speed MOSFETs and IGBTs that operate up to +600V. It has a buffered output stage with all NMOS transistors designed for high pulse current driving capability and minimum cross-conduction.

Fairchild's high-voltage process and common-mode noise canceling techniques provide stable operation of the high-side driver under high dv/dt noise circumstances. An advanced level-shift circuit offers high-side gate driver operation up to $V_S = -9.8V$ (typical) for $V_{BS} = 15V$.


The UVLO circuit prevents malfunction when V_{BS} is lower than the specified threshold voltage.

The high-current and low-output voltage drop feature makes this device suitable for sustained switch driver and energy recovery switch driver in the Plasma Display Panel application, motor drive inverter, switching power supply, and high-power DC-DC converter applications.

8-SOP



Ordering Information

Part Number	Package	Operating Temperature Range	 Eco Status	Packing Method
FAN7371M ⁽¹⁾	8-SOP	-40°C ~ 125°C	RoHS	Tube
FAN7371MX ⁽¹⁾				Tape & Reel

Note:

1. These devices passed wave soldering test by JESD22A-111.



For Fairchild's definition of Eco Status, please visit: http://www.fairchildsemi.com/company/green/rohs_green.html.

Typical Application Diagrams

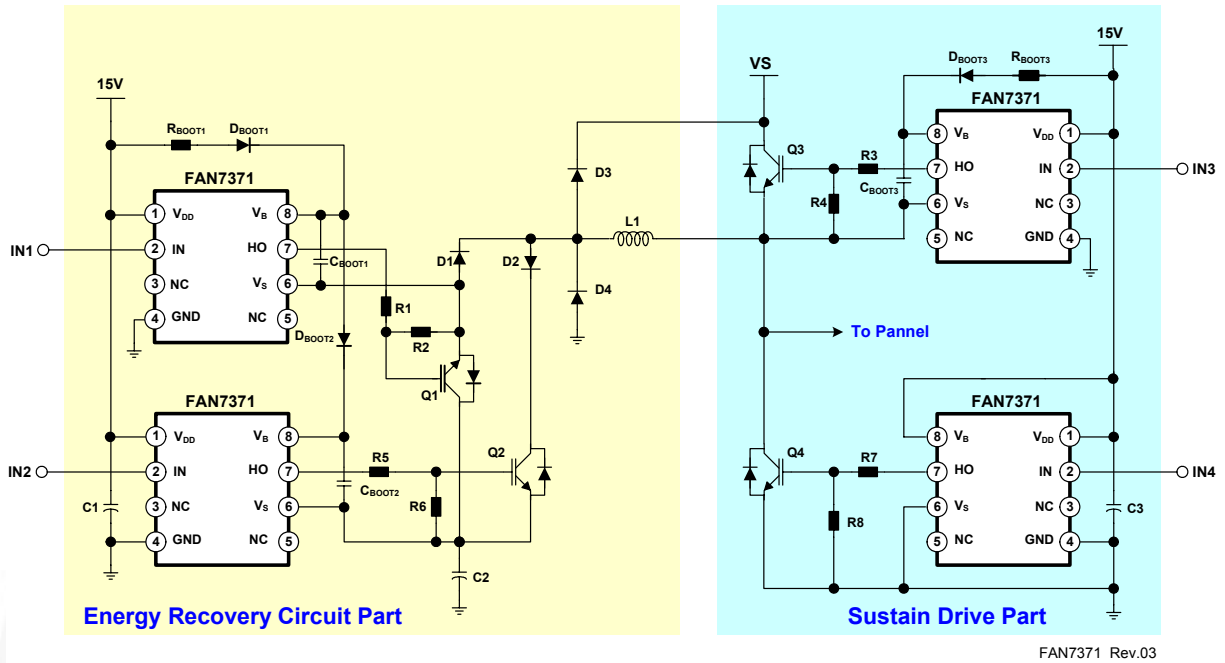


Figure 1. Floated Bidirectional Switch and Half-Bridge Driver: PDP application

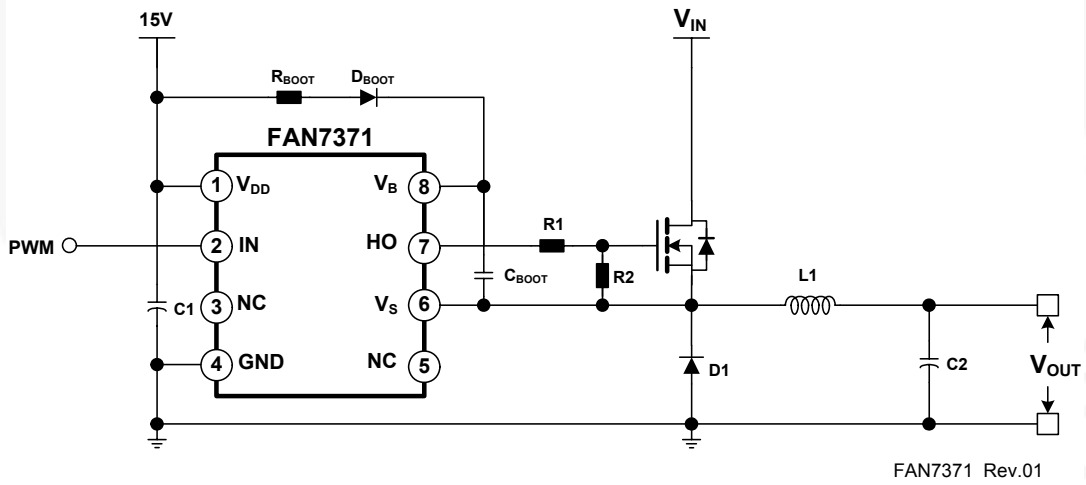


Figure 2. Step-Down (Buck) DC-DC Converter Application

Internal Block Diagram

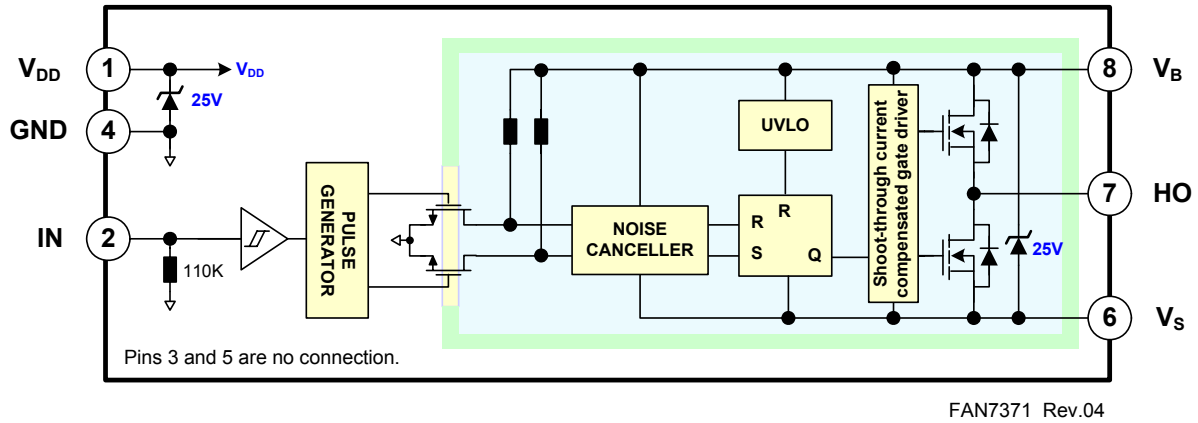


Figure 3. Functional Block Diagram

Pin Configuration

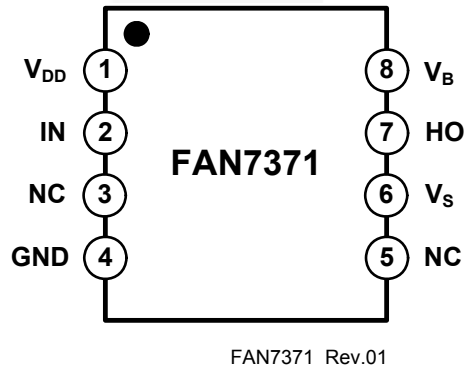


Figure 4. Pin Configuration (Top View)

Pin Definitions

Pin #	Name	Description
1	V _{DD}	Supply Voltage
2	IN	Logic Input for High-Side Gate Driver Output
3	NC	No Connection
4	GND	Ground
5	NC	No Connection
6	V _S	High-Voltage Floating Supply Return
7	HO	High-Side Driver Output
8	V _B	High-Side Floating Supply

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. $T_A=25^{\circ}\text{C}$ unless otherwise specified.

Symbol	Characteristics	Min.	Max.	Unit
V_S	High-Side Floating Offset Voltage	$V_B - V_{SHUNT}$	$V_B + 0.3$	V
V_B	High-Side Floating Supply Voltage ⁽²⁾	-0.3	625.0	V
V_{HO}	High-Side Floating Output Voltage	$V_S - 0.3$	$V_B + 0.3$	V
V_{DD}	Low-Side and Logic Supply Voltage ⁽²⁾	-0.3	V_{SHUNT}	V
V_{IN}	Logic Input Voltage	-0.3	$V_{DD} + 0.3$	V
dV_S/dt	Allowable Offset Voltage Slew Rate		± 50	V/ns
P_D	Power Dissipation ^(3, 4, 5)		0.625	W
θ_{JA}	Thermal Resistance		200	$^{\circ}\text{C}/\text{W}$
T_J	Junction Temperature	-55	+150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature	-55	+150	$^{\circ}\text{C}$
T_A	Operating Ambient Temperature	-40	+125	$^{\circ}\text{C}$

Notes:

- This IC contains a shunt regulator on V_{DD} and V_{BS} with a normal breakdown voltage of 25V. Please note that this supply pin should not be driven by a low-impedance voltage source greater than the V_{SHUNT} specified in the Electrical Characteristics section
- Mounted on 76.2 x 114.3 x 1.6mm PCB (FR-4 glass epoxy material).
- Refer to the following standards:
JESD51-2: Integral circuits thermal test method environmental conditions, natural convection, and
JESD51-3: Low effective thermal conductivity test board for leaded surface mount packages.
- Do not exceed power dissipation (P_D) under any circumstances.

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Unit
V_{BS}	High-Side Floating Supply Voltage	$V_S + 10$	$V_S + 20$	V
V_S	High-Side Floating Supply Offset Voltage	$6 - V_{DD}$	600	V
V_{HO}	High-Side Output Voltage	V_S	V_B	V
V_{IN}	Logic Input Voltage	GND	V_{DD}	V
V_{DD}	Supply Voltage	10	20	V

Electrical Characteristics

$V_{BIAS}(V_{DD}, V_{BS})=15.0V$, $T_A = 25^\circ C$, unless otherwise specified. The V_{IN} and I_{IN} parameters are referenced to GND. The V_O and I_O parameters are relative to V_S and are applicable to the respective output HO.

Symbol	Characteristics	Test Condition	Min.	Typ.	Max.	Unit
POWER SUPPLY SECTION						
I_{QDD}	Quiescent V_{DD} Supply Current	$V_{IN}=0V$ or $5V$		25	70	μA
I_{PDD}	Operating V_{DD} Supply Current	$f_{IN}=20KHz$, No Load		35	100	μA
BOOTSTRAPPED SUPPLY SECTION						
V_{BSUV+}	V_{BS} Supply Under-Voltage Positive Going Threshold Voltage	$V_{BS}=\text{Sweep}$	8.2	9.2	10.2	V
V_{BSUV-}	V_{BS} Supply Under-Voltage Negative Going Threshold Voltage	$V_{BS}=\text{Sweep}$	7.5	8.5	9.5	V
V_{BSHYS}	V_{BS} Supply Under-Voltage Lockout Hysteresis Voltage	$V_{BS}=\text{Sweep}$		0.7		V
I_{LK}	Offset Supply Leakage Current	$V_B=V_S=600V$			10	μA
I_{QBS}	Quiescent V_{BS} Supply Current	$V_{IN}=0V$ or $5V$		60	120	μA
I_{PBS}	Operating V_{BS} Supply Current	$C_{LOAD}=1nF$, $f_{IN}=20KHz$, rms Value		1.0	2.8	mA
SHUNT REGULATOR SECTION						
V_{SHUNT}	V_{DD} and V_{BS} Shunt Regulator Clamping Voltage	$I_{SHUNT}=5mA$	24	25		V
INPUT LOGIC SECTION						
V_{IH}	Logic "1" Input Voltage		2.5			V
V_{IL}	Logic "0" Input Voltage				0.8	V
I_{IN+}	Logic Input High Bias Current	$V_{IN}=5V$		45	70	μA
I_{IN-}	Logic Input Low Bias Current	$V_{IN}=0V$			2	μA
R_{IN}	Input Pull-down Resistance		70	110		$K\Omega$
GATE DRIVER OUTPUT SECTION						
V_{OH}	High Level Output Voltage ($V_{BIAS} - V_O$)	No Load			1.2	V
V_{OL}	Low Level Output Voltage	No Load			30	mV
I_{O+}	Output High, Short-Circuit Pulsed Current ⁽⁶⁾	$V_{HO}=0V$, $V_{IN}=5V$, $PW \leq 10\mu s$	3.0	4.0		A
I_{O-}	Output Low, Short-Circuit Pulsed Current ⁽⁶⁾	$V_{HO}=15V$, $V_{IN}=0V$, $PW \leq 10\mu s$	3.0	4.0		A
V_S	Allowable Negative V_S pin Voltage for IN Signal Propagation to HO			-9.8	-7.0	V

Note:

6 These parameters guaranteed by design.

Dynamic Electrical Characteristics

$V_{DD}=V_{BS}=15V$, $GND=0V$, $C_{LOAD}=1000pF$, $T_A=25^\circ C$, unless otherwise specified.

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
t_{on}	Turn-on Propagation Delay Time	$V_S=0V$		150	210	ns
t_{off}	Turn-off Propagation Delay Time	$V_S=0V$		150	210	ns
t_r	Turn-on Rise Time			25	50	ns
t_f	Turn-off Fall Time			15	40	ns

Typical Characteristics

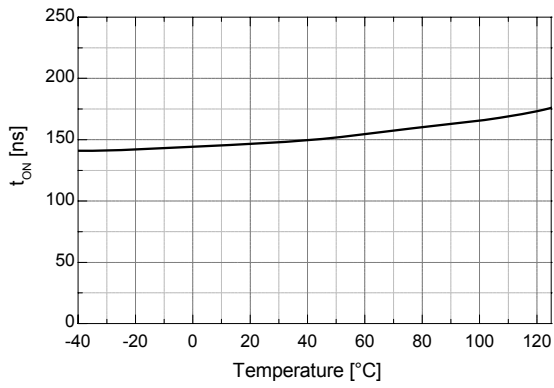


Figure 5. Turn-on Propagation Delay vs. Temperature

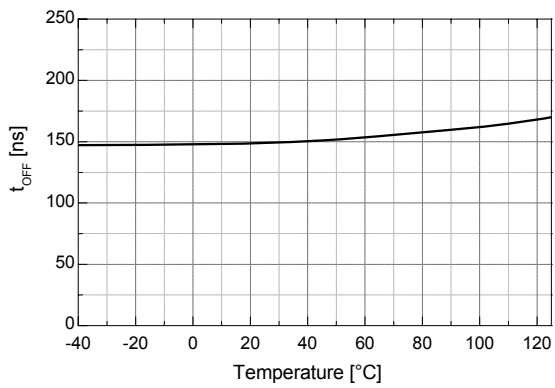


Figure 6. Turn-off Propagation Delay vs. Temperature

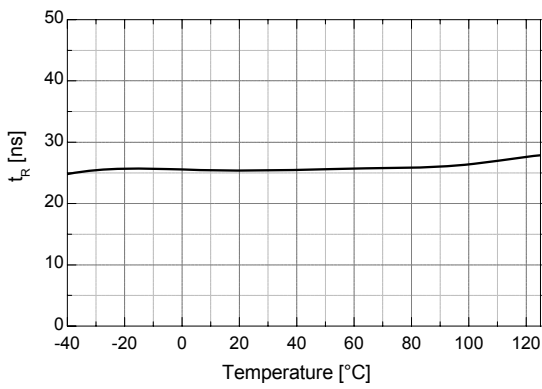


Figure 7. Turn-on Rise Time vs. Temperature

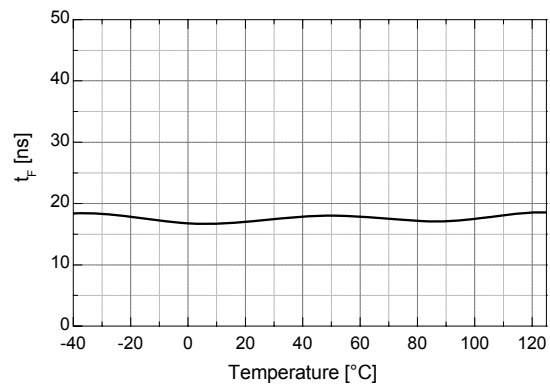


Figure 8. Turn-off Fall Time vs. Temperature

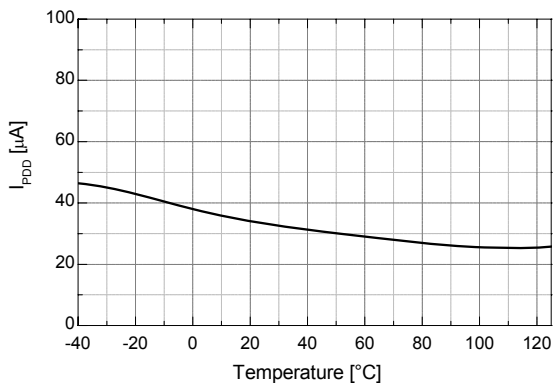


Figure 9. Operating V_{DD} Supply Current vs. Temperature

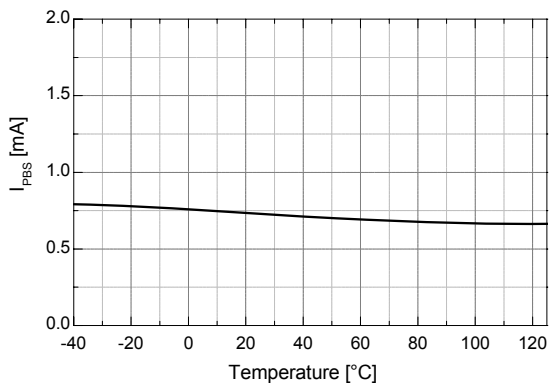


Figure 10. Operating V_{BS} Supply Current vs. Temperature

Typical Characteristics (Continued)

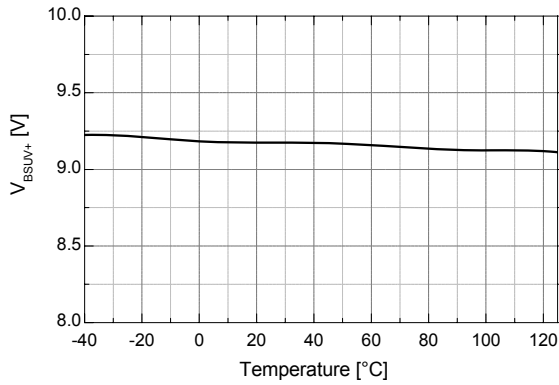


Figure 11. V_{BS} UVLO+ vs. Temperature

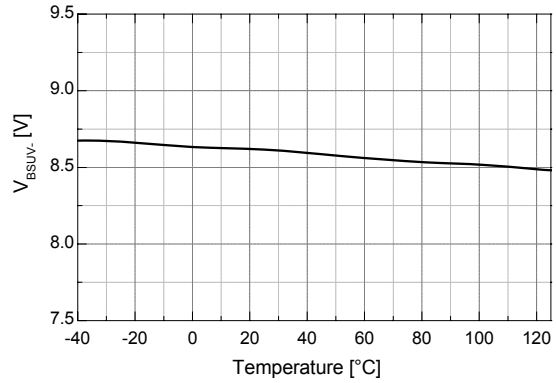


Figure 12. V_{BS} UVLO- vs. Temperature

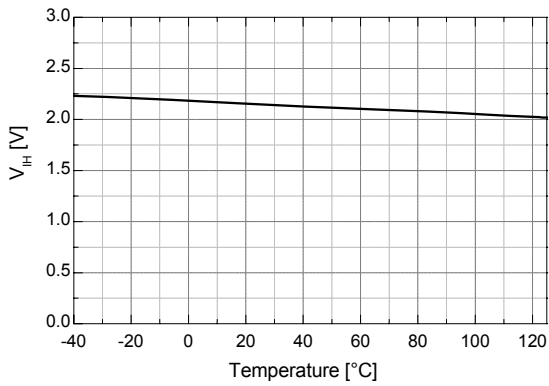


Figure 13. Logic High Input Voltage vs. Temperature

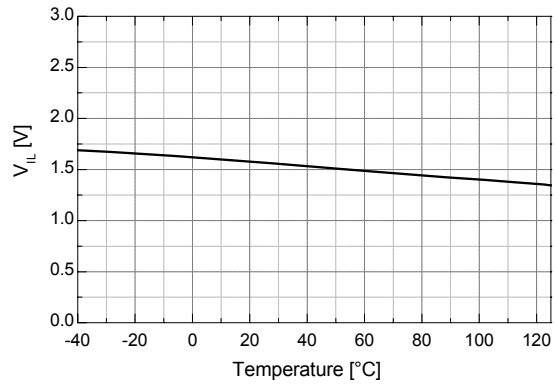


Figure 14. Logic Low Input Voltage vs. Temperature

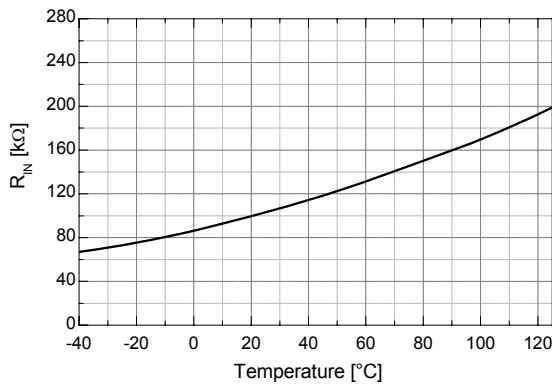


Figure 15. Input Pull-Down Resistance vs. Temperature.

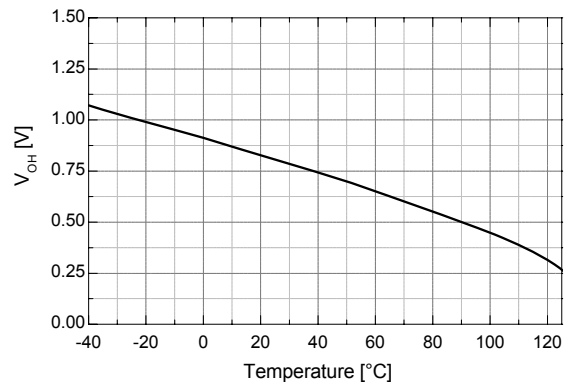


Figure 16. High-Level Output Voltage vs. Temperature

Typical Characteristics (Continued)

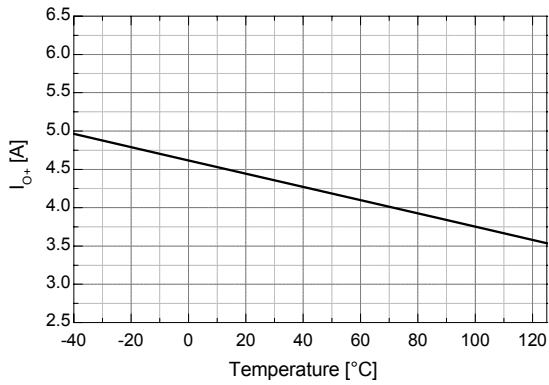


Figure 17. Output High, Short-Circuit Pulsed Current vs. Temperature

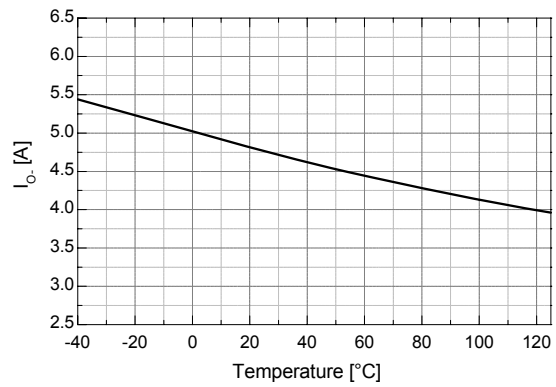


Figure 18. Output Low, Short-Circuit Pulsed Current vs. Temperature

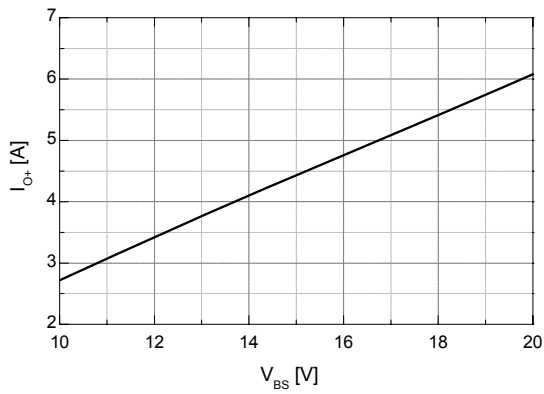


Figure 19. Output High, Short-Circuit Pulsed Current vs. Supply Voltage

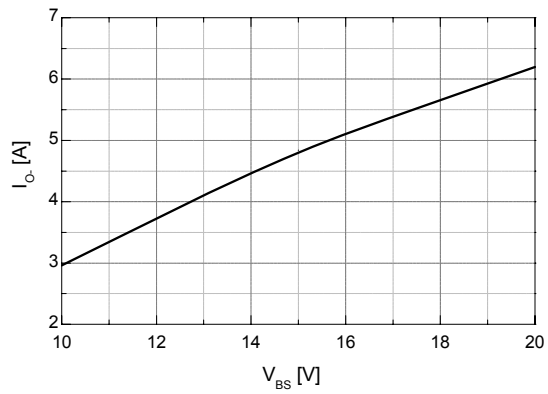


Figure 20. Output Low, Short-Circuit Pulsed Current vs. Supply Voltage

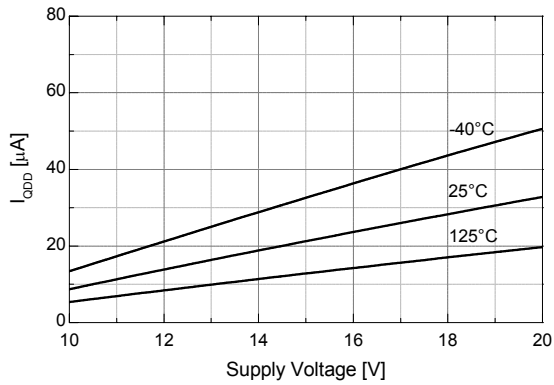


Figure 21. Quiescent V_{DD} Supply Current vs. Supply Voltage

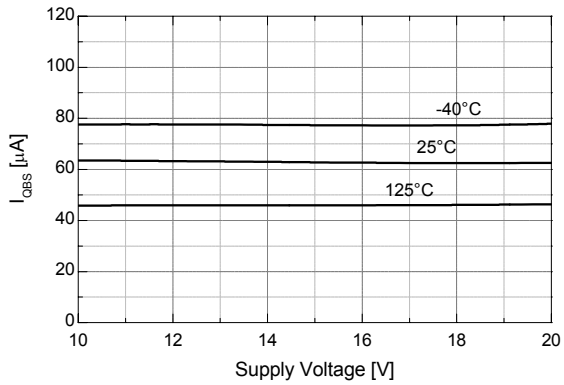


Figure 22. Quiescent V_{BS} Supply Current vs. Supply Voltage

Switching Time Definitions

Timing Diagram

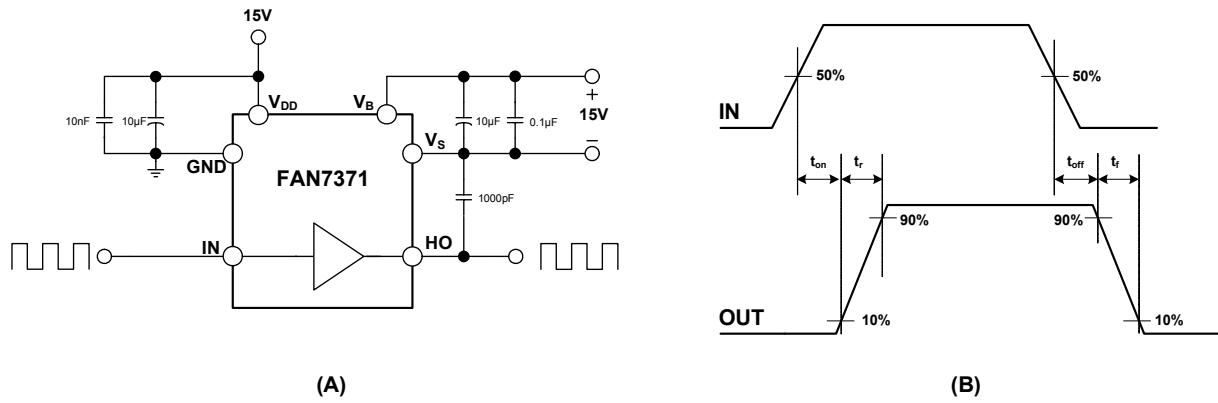


Figure 23. Switching Time Test Circuit and Waveform Definitions

Physical Dimensions

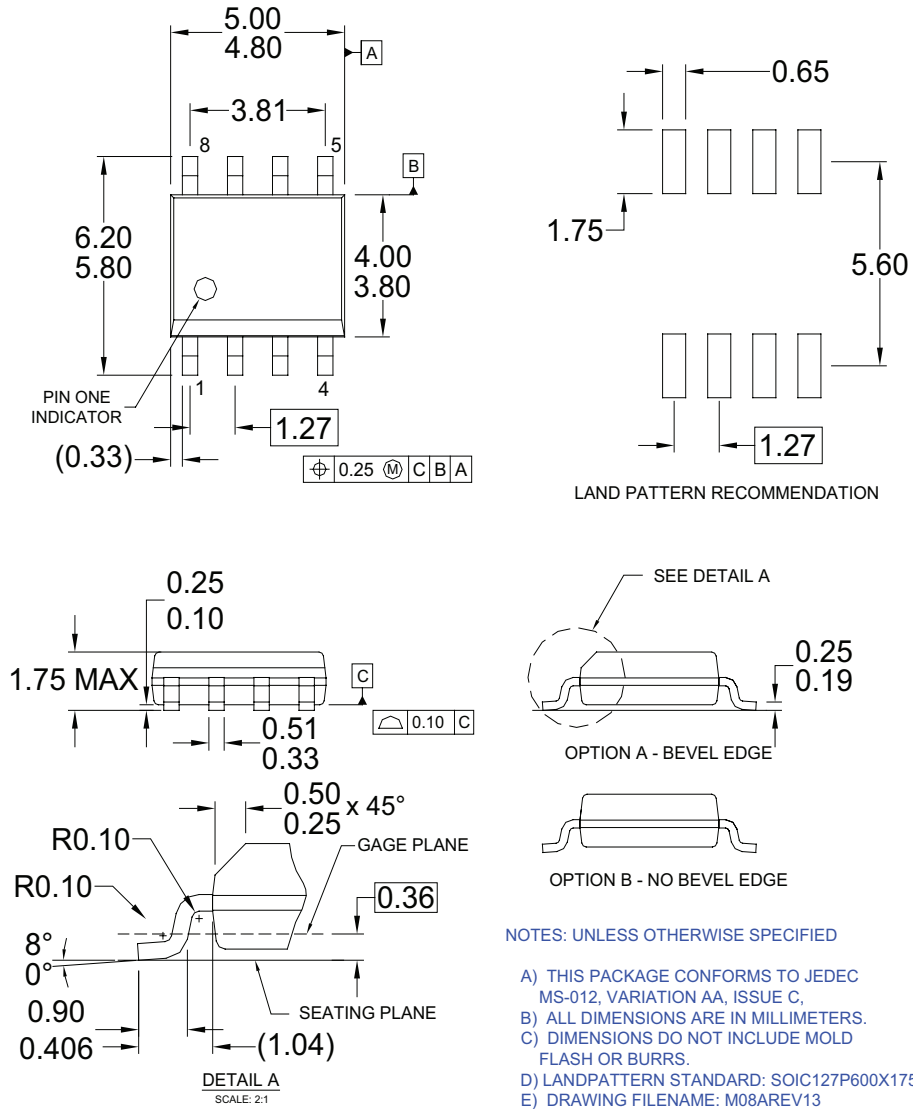


Figure 24. 8-Lead Small Outline Package (SOP)

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

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